L.N. 50 of 2007

PRODUCT SAFETY ACT
(CAP. 427)

Restriction of Use of Hazardous Substances in Electrical and Electronic Equipment (Amendment) Regulations, 2007

IN exercise of the powers conferred by articles 38 to 40 of the Product Safety Act, the Minister for Competitiveness and Communications, on the advice of the Malta Standards Authority, has made the following regulations:-

Citation, commencement and scope.

1. (1) The title of these regulations is the Restriction of Use of Hazardous Substances in Electrical and Electronic Equipment (Amendment) Regulations, 2007 and they shall be read and construed as one with the Restriction of Use of Hazardous Substances in Electrical and Electronic Equipment Regulations, 2004, hereinafter referred to as "the principal regulations".

L.N. 396 of 2004.

(2) These regulations shall be deemed to have come into force on the 1st July 2006.

(3) These regulations implement the requirements of Commission Decisions:

Commission Decision 2006/690/EC of 12 October 2006 amending, for the purposes of adapting to technical progress, the Annex to Directive 2002/95/EC of the European Parliament and of the Council as regards exemptions for applications of lead in crystal glass.

Commission Decision 2006/691/EC of 12 October 2006 amending, for the purposes of adapting to technical progress, the Annex to Directive 2002/95/EC of the European Parliament and of the Council as regards exemptions for applications of lead and cadmium.

Commission Decision 2006/692/EC of 12 October 2006 amending, for the purposes of adapting to technical progress, the Annex to Directive 2002/95/EC of the European Parliament and of the Council as regards exemptions for applications of hexavalent chromium.

2. For Schedule I of the principal regulations there shall be substituted the following:

“Schedule I

(Regulation 4(2))

Applications of lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE) which are exempt from the requirements of regulation 4(2)

Item No. Application

1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.

2. Mercury in straight fluorescent lamps for general purposes not exceeding:

— halophosphate	10 mg
— triphosphate with normal lifetime	5 mg
— triphosphate with long lifetime	8 mg.

3. Mercury in straight fluorescent lamps for special purposes.

4. Mercury in other lamps not specifically mentioned in this Schedule.

5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.

6. Lead as an alloying element in steel containing up to 0,35 % lead by weight, aluminium containing up to 0,4 % lead by weight and as a copper alloy containing up to 4 % lead by weight.

7. (a) Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85 % lead),

(b) Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications,

(c) Lead in electronic ceramic parts (e.g. piezoelectronic devices).

8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC[3] amending Directive 76/769/EEC2[4] relating to restrictions on the marketing and use of certain dangerous substances and preparations.

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[3] OJ L 186, 12.7.1991, p. 59.

[4] OJ L 262, 27.9.1976, p. 201.

9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.

9a. Deca BDE for polymeric applications.

9b. Lead in lead-bronze bearing shells and bushes.

10. –

11. Lead used in compliant pin connector systems.

12. Lead as a coating material for the thermal conduction module c-ring.

13. Lead and cadmium in optical and filter glass.

14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight.

15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

16. Lead in linear incandescent lamps with silicate coated tubes.

17. Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for professional reprography applications.

18. Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi2O5:Pb) as well as when used as speciality lamps for diazo-printing reprography, lithography, insect traps, photochemical and curing processes containing phosphorssuch as SMS ((Sr,Ba)2MgSi2O7:Pb).

19. Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL).

20. Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCD).

21. Lead and cadmium in printing inks for the application of enamels on borosilicate glass.

22. Lead as impurity in RIG (rare earth iron garnet) Faraday rotators used for fibre optic communications systems.

23. Lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with NiFe lead frames and lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with copper lead frames.

24. Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors.

25. Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays (SED) used in structural elements; notably in the front and rear glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit and frit ring as well as in print pastes.

26. Lead oxide in the glass envelope of Black Light Blue (BLB) lamps.

27. Lead alloys as solder for transducers used in high-powered (designated to operate for several hours at acoustic power levels of 125 dB SPL and above) loudspeakers.'

28. Hexavalent chromium in corrosion preventive coatings of unpainted metal sheetings and fasteners used for corrosion protection and Electromagnetic Interference Shielding in equipment falling under category three of Directive 2002/96/EC (IT and telecommunications equipment). Exemption granted until 1 July 2007.'

29. Lead bound in crystal glass as defined in Annex I (Categories 1, 2, 3 and 4) of Council Directive 69/493/EEC.[5]"

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[5] OJ L 326, 29.12.1969, p. 36. Directive as last amended by 2003 Act of Accession.

Ippubblikat mid-Dipartiment ta' l-Informazzjoni (doi.gov.mt) — Valletta — *Published by the Department of Information (doi.gov.mt) — Valletta*
Mitbugh fl-Istamperija tal-Gvern — *Printed at the Government Printing Press*
Prezz/*Price*
Lm0.08 (€0.19)